

## ABSTRACT OF THE DISCLOSURE

A semiconductor device mountable on a wiring board with the bottom surface being opposed to the wiring board. The semiconductor device includes: a semiconductor chip; a mold resin encapsulating the semiconductor chip; a first heat spreader joined to the semiconductor chip on the bottom surface side, and extending in almost parallel with the bottom surface with both ends thereof protruding from an edge of the mold resin, the first heat spreader being capable of being joined to the wiring board at the both ends thereof; and a second heat spreader joined to the semiconductor chip on a top surface side, and extending in almost parallel with the bottom surface to cross with the first heat spreader with both ends thereof protruding from the edge of the mold resin, the second heat spreader being capable of being joined to the wiring board at the both ends thereof. One of the first and second heat spreaders is a lead frame electrically connected to the semiconductor chip.